

## PATENT ABSTRACTS OF JAPAN

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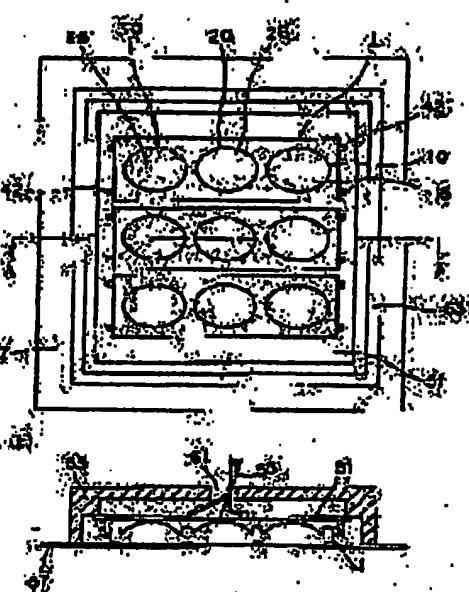
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## (54) MANUFACTURE OF LIGHT EMISSION DIODE LAMP

## (57)Abstract

**PURPOSE:** To improve workability during resin sealing of a reflection type light emission diode.

**CONSTITUTION:** Arrays of three light emission diodes each are arranged in three lines on a board 51 and stored into a lamp case 53. The front face of the lamp case 53 containing radiation faces 16, 26, 36 of light emission diodes 10, 20, 30 of a light emission diode array 1 is covered with a heat-resistant adhesive tape 57 with no clearances. With the front face of the lamp case 53 turned down, a black epoxy resin is injected from the rear side of the lamp case 53 to defoam in a vacuum. After the light emission diode arrays 1 and the board 51 are pervaded full with the resin, it is cured in a dry furnace at about 80° C; finally, the adhesive tape 57 is peeled off.



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